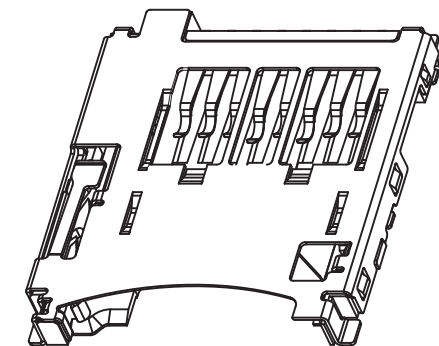
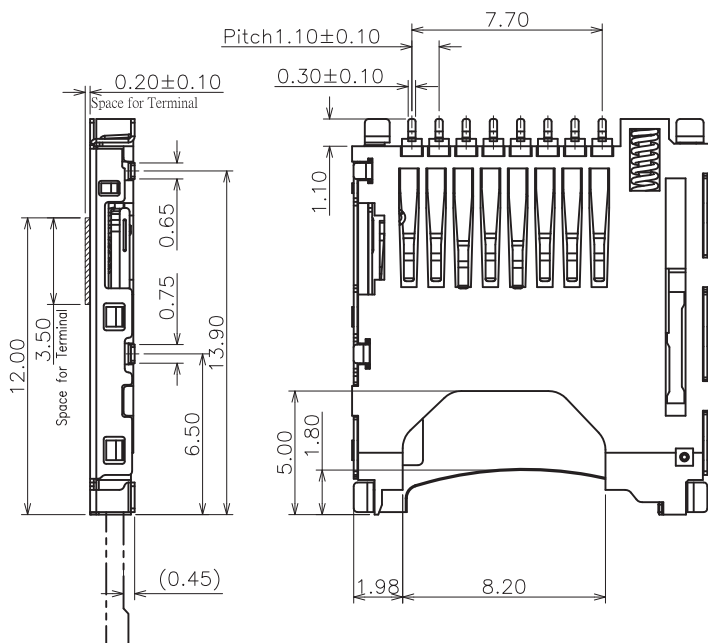
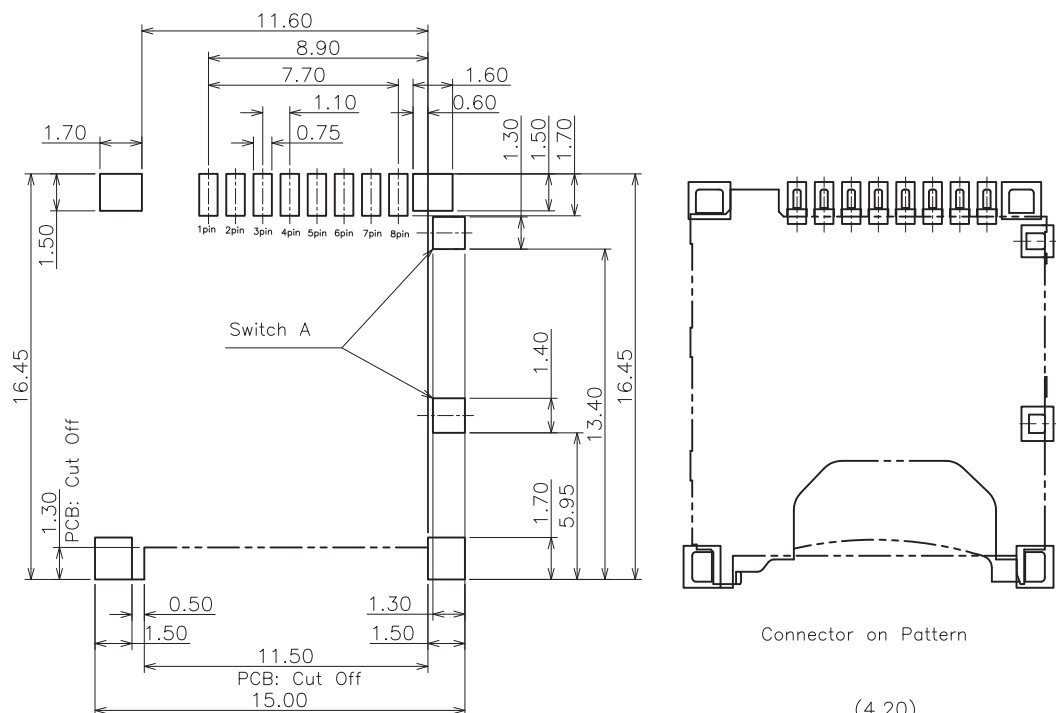




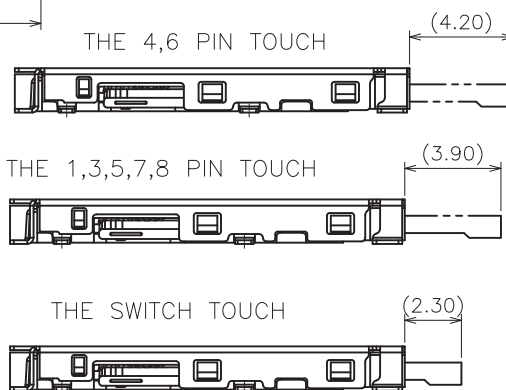
CARD OUT	
CARD LOCK	
CARD PUSH END	

CONTACT AREA :5μ" Au PLATED /20μ" Au PLATED OVER Ni
SOLDER AREA:5μ" Au PLATED OVER Ni

DESCRIPTION: MicroSD Memory Card Socket Reverse Type



Recommended PCB Pattern Layout
General Tolerance: ± 0.05



Note:

1. Material: See Table
2. Finishes: See Table
 - 2-1 Contact: Nickel Underplated
3u" Gold Plating on Contact Area, Gold Flash on Solder Tail
 - 2-2 Switch & Detect: Nickel Underplated
5u" Gold Plating on Contact Area
 - 2-3 Shell: Gold Flash Over Nickel Underplated on Solder Pad
3. Coplanarity of Solder tails : 0.10MAX.
Misalignment of Solder Tail From "Z"
Upper Direction 0.05 MAX. , Lower Direction 0.1 MAX.
4. Mechanical Specification:
Repeated 10000 Times Mating and Unmating Cycles and Still Meet Electrical Characteristics
5. Electrical Specification:
 - 5-1 Rated Current (Per Contact): 0.5Amps MAX and Temperature Rise Should be 30°C MAX.
 - 5-2 Insulation Resistance(LR): 1000 Megohms MIN.
 - 5-3 Dielectric With Standing Voltage: 500VAC
 - 5-4 Contact Resistance : 100 Milliohms MAX.
6. "▼" sign, for the QC testing and focus IPQC

9	Coil Spring	J5F319KVSX360005	Stainless Steel		Ni over all
8	Slider	J8F301K08BKS	Polyamide 9T	White	
7	Lock Spring	J5F318KTSWXX0003	Stainless Steel		
6	Crank-Axle	J5F320KTSW000004	Stainless Steel		
5	Shell	J5F317KT00XXX001	Stainless Steel		Selective-Au over Ni
4	Switch	J5F318KQSWXX002	PHOS.-Bronze		Selective-Au over Ni
3	Detect	J5F318KQSWXX001	PHOS.-Bronze		Selective-Au over Ni
2	Contact	J4F301K1XXX0001	PHOS.-Bronze		Selective-Au over Ni
1	Housing	J8F301KXBKXX	PA9T & LCP	Black	
NO	PART NAME	PART NO.	MATERIALS	COLOR	FINISHS

RoHS Compliant

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PCB CONNECTORS
Cable ASSEMBLIES

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DRAWING BY CY

CHECKED BY GENIUS

UNIT / mm

SCALE 1 : 1

DATE

SIZE A4

X, ± 0.50

.X, ± 0.30

.XX, ± 0.20

.XXX, $\pm$

ANG $\pm$

PPOJECTION

照片框

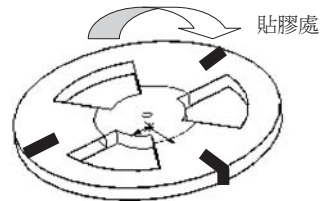
ORDER INFORMATION

TFC-WPAE13R-08-LF
SERIES T T T T LEADFREE
90°SMT REEL 08WAY
EAR 13.9mm
UPPER CONTACT
PUSH PUSH

DESCRIPTION: MicroSD Memory Card Socket Reverse Type

動作說明：

- 1.將成品放入 REEL 中，如右圖所示。
- 2.依序放置，放滿換盤(1000PCS)。
- 3.卷盤裝滿後周圍要用膠帶固定，防止載帶鬆動。(如下圖示)



動作說明：

- 1.將裝滿的十二盤產品放入 PE 袋內並加入一包乾燥劑，包好後放置於箱中。
- 2.封箱時，周圍部份都要貼上膠帶。

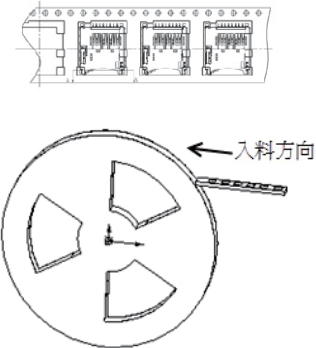
注意事項：

- 1.放置成品時，勿傷及錫腳。
- 2.在卷料時載帶應於卷盤軸上的槽對齊，並用膠帶固定好後再卷料。

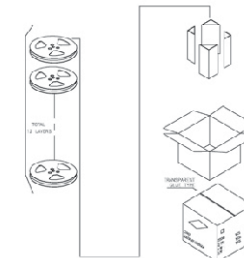
注意事項：

- 1.放置成品時，勿壓 REEL 邊緣。

圖示：

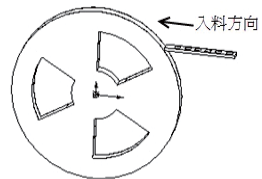


圖示：

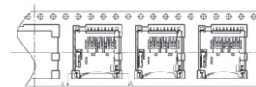


PART NO.	REEL		CARTON		Weight (KG)	
	Dimension(mm)	QTY(PCS)	Dimension(mm)	QTY (PCS)	N.W	G.W
TFC-WPAE13R-08	Ø330x38(H)	1000	350(L)x350(W) x 380(H)	1000x12(Reel)= 12000	5	12.5

a.



c.



照片框

RoHS Compliant

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DRAWING BY CY

CHECKED BY GENIUS

UNIT / mm

SCALE 1 : 1

DATE

SIZE A4

PPOJECTION

X, ±
.X ±
.XX ±
.XXX ±
ANG ±

ORDER INFORMATION

TFC-WPAE13R-08-LF
SERIES T T T T LEADFREE
90°SMT REEL EAR 13.9mm
UPPER CONTACT
PUSH PUSH

DESCRIPTION: